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PROSECUTION OF THE SUBJECT APPLICATION

Applicants: B. Kim et al. Attorney Docket No. SEMT119849

Application No.: 10/700,782 Group Art Unit: 1753

Filed: November 3, 2003 Examiner: Edna Wong

Title: BATH AND METHOD FOR HIGH RATE COPPER DEPOSITION

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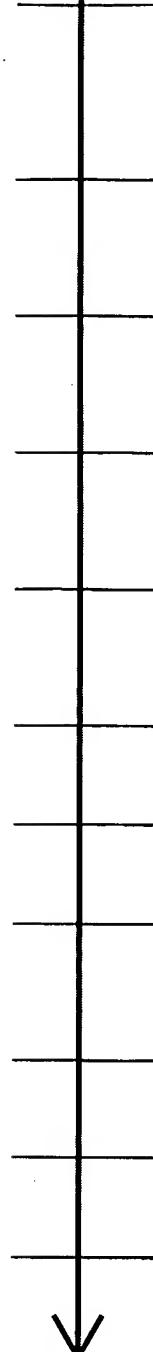
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<u>/Edna Wong/</u>	04/18/2007

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